



Belon Technology **IoT Intelligence**

BX7258ai

Belon Solutions www.belon.cn **WiFi/BLE Dual-mode Low-power Wireless Module**

BX7258ai Module Datasheet

WiFi/BLE Dual-mode Low-power Wireless Module



Version: 2.0

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Catalogue

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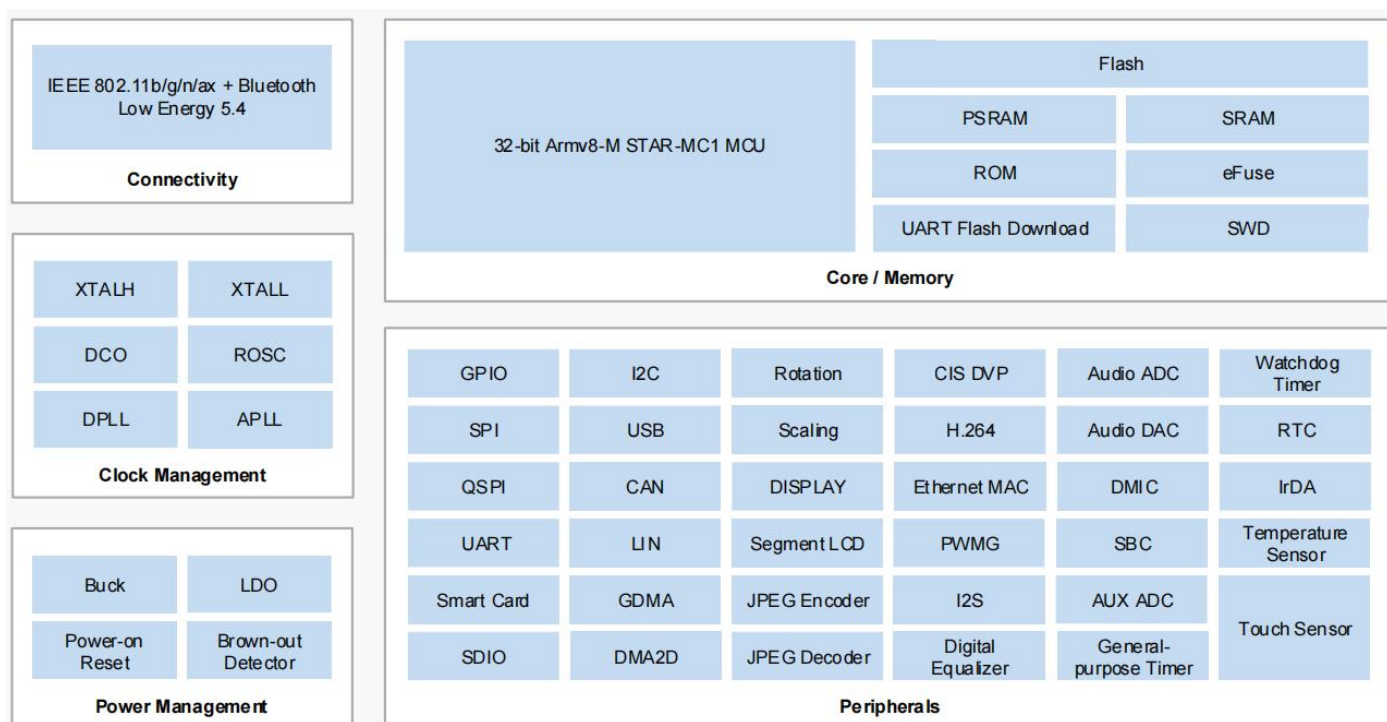
Document History

Version	Created Date	Modified Date	Modified By	Remarks
1.0	2025-04-10		xdx	Initial Version
2.0		2026-1-15	Xdx	Modify IO Port Name



1. Introduction

The BX7258ai module is a low-power WiFi module developed by Belon Technology. It consists of a BK7258 SOC and peripheral components. The BX7258ai is a highly integrated ,single-antenna, single-band 2.4 GHz Wi-Fi 6 (IEEE 802.11b/g/n/ax) and Bluetooth 5.4 low-energy (LE) dual-mode IoT module. Utilizing multi-peripheral packaging and ultra-low-power chip technology, the BX7258ai delivers a highly integrated, efficient, and secure product environment with minimal power consumption for IP cameras, HMI applications, smart locks, and other advanced IoT applications. **As shown in Figure 1:**





2.Features

CPU and Storage

- Built-in ARMv8-M Star (M33F) processor, with a maximum main frequency of up to 480 MHz
- 8MB Flash
- 16MB PSRAM
- 640KB SRAM
- 64KB ROM

Wi-Fi

- IEEE 802.11b/g/n/ax
- Channel bandwidths of 20MHz and 40MHz
- Supports Downlink Multi-User, Multiple Input and Multiple Output (DL MU-MIMO)
- Supports Orthogonal Frequency Division Multiple Access (OFDMA)
- Supports Target Wake Time (TWT)
- Integrated Bluetooth/Wi-Fi Coexistence (PTA)
- Transmit power up to +20 dBm
- Receive sensitivity: -99 dBm
- Antenna gain: 2.5dBi

Bluetooth

- Supports Bluetooth LE 5.4 standard
- Supports Bluetooth Low Energy 1 Mbps and long-range modes (125 Kbps and 500 Kbps)



- Transmit power: +6 dBm
- Receive sensitivity: -97 dBm
- Antenna gain: 2.5dBi

Peripherals

- 48x GPIOs
- 2x SPI, 2x QSPI
- 3x UART: 1 port with hardware flow control and supports Flash download
- 1x smart card controller
- 1x SDIO, 2x I2C, 1x CAN controller with CAN FD
- 1x High-Speed USB2.0 (HS)
- 1x display controller supporting RGB 565 and 8080 interfaces
- 1x segment LCD controller for up to 4 × 32 segments
- 1x 8-bit CIS DVP interface
- 1x 720p H.264 video encoder
- 1x Ethernet MAC interface
- 5x 32-bit PWM channels
- 3x I2S
- 2x audio ADC, 1x audio DAC
- 12-bit AUX ADC, up to 11 channels
- 1x touch sensor, up to 16 touch sensing I/Os

Antenna

- Supports external antenna (on-board antenna by default)

Operating Conditions



- Operating voltage / Supply voltage: 2.0 ~ 3.6V
- Operating ambient temperature: -40 ~ 85°C

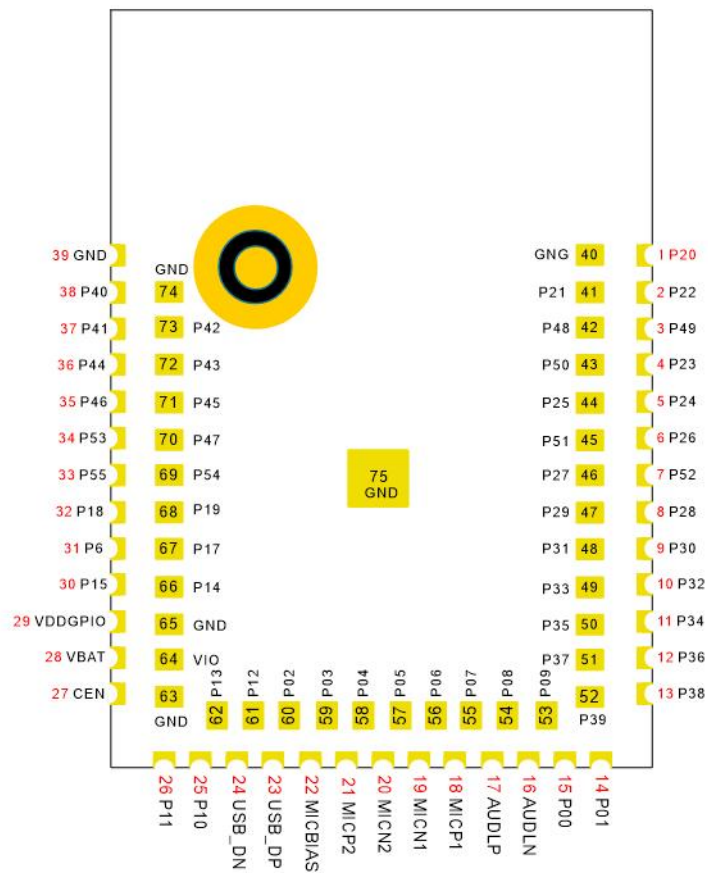
3.Main Application Areas

- HMI (Human-Machine Interface) applications, smart home / home appliances
- Home appliances
- Smart lighting
- Baby monitors
- Smart public transportation
- IP cameras, smart door locks
- Industrial wireless control



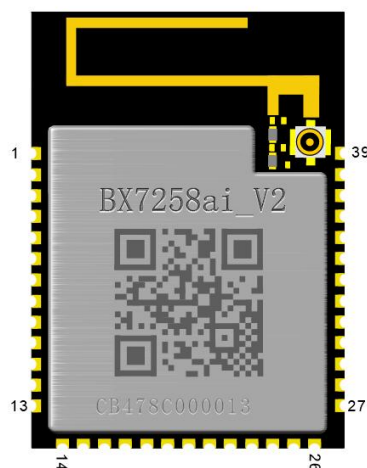
4.Module Interface

4.1 Pin Definition

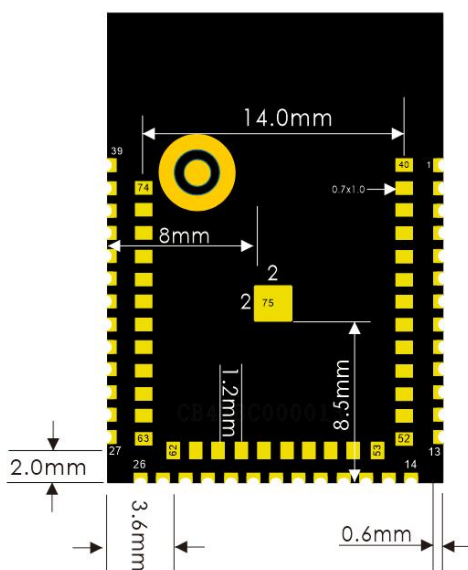




4.2 Front View



4.3 Back View





4.4 Pin definition

Pinout Definition as Shown: BX7258ai Pin Arrangement Description

Pin	Symbol	IO	Function
1	P20	I/O	● GPIO20 ● RGB_R6 ● I2C0_SCL ● SWCLK ● I8080_D9
2	P22	I/O	● CLK26M ● ADC5 ● QSPI0_SCK ● RGB_R4 ● I8080_CSX ● SEG8
3	P49	I/O	● ENET_RXD0 ● RGB_R1 ● I8080_D17
4	P23	I/O	● ADC3



Pin	Symbol	IO	Function
			● QSPI0_CS ● RGB_R3 ● I8080_RESET ● SEG7
5	P24	I/O	● LPO_CLK ● PWMG0_PWM4 ● ADC2 ● QSPI0_IO0 ● RGB_G7 ● I8080_RSX ● SEG6
6	P26	I/O	● QSPI0_IO2 ● RGB_G5 ● I8080_RDX ● SEG4
7	P52	I/O	● ENET_TXD0 ● RGB_G0
8	P28	I/O	● I2S_MCLK



Pin	Symbol	IO	Function
			● ADC4 ● TOUCH2 ● CLK_AUXS_CIS ● SEG18
9	P30	I/O	● CIS_HSYNC ● UART2_RX ● LIN_RXD ● TOUCH4 ● SC_CLK ● SEG20
10	P32	I/O	● CIS_PXD0 ● PWMG1_PWM0 ● ENET_MDIO ● TOUCH6 ● SC_RSTN ● SEG22
11	P34	I/O	● CIS_PXD2 ● PWMG1_PWM2



Pin	Symbol	IO	Function
			• ENET_RXD1 • TOUCH8 • SPI0_CSN • SEG24
12	P36	I/O	• CIS_PXD4 • PWMG1_PWM4 • ENET_TXD0 • TOUCH10 • SPI0_MISO • SEG26
13	P38	P	• CIS_PXD6 • I2C1_SCL • ENET_TXEN • TOUCH12 • COM4 • SEG28
14	P01	I/O	• UART1_RX • I2C1_SDA



Pin	Symbol	IO	Function
			• SWDIO • SC_CLK • ADC13 • LIN_RXD
15	P00	I/O	• UART1_TX • I2C1_SCL • SWCLK • SC_IO • ADC12 • LIN_TXD
16	AUDLN	AO	Audio left channel negative output
17	AUDLP	AO	Audio left channel positive output
18	MICP1	AO	Microphone 1 positive input
19	MICN1	AO	Microphone 1 negative input
20	MICN2	AO	Microphone 2 negative input
21	MICP2	AO	Microphone 2 positive input
22	MICBIAS	AO	Microphone bias output



Pin	Symbol	IO	Function
23	USB_DP	I/O	USB D+
24	USB_DN	I/O	USB D-
25	P10	I/O	● DL_UART_RX ● SDIO_DATA2 ● CLK_AUXS_CIS ● UART0_RX ● Module Programming & Authorization User UART
26	P11	I/O	● DL_UART_TX ● UART0_TX ● SDIO_DATA3 ● Module Programming & Authorization User UART
27	CEN	AI	Active-low reset, high-level valid (internal pull-up)
28	VBAT	P	Module power supply pin
29	VDDGPIO	AO	GPIO power supply
30	P15	I/O	● SDIO_CMD ● SPI0_CSN ● I2C1_SDA



Pin	Symbol	IO	Function
			● RGB_DISP ● I8080_D14 ● SEG15
31	P16	I/O	● SDIO_DATA0 ● SPI0_MOSI ● RGB_DE ● I8080_D13 ● SEG14
32	P18	I/O	● SDIO_DATA2 ● PWMG0_PWM0 ● RGB_VSYNC ● I8080_D11 ● SEG12
33	P55	I/O	● ENET_REF_CLK ● RGB_B0
34	P53	I/O	● ENET_TXD1 ● RGB_B2
35	P46	I/O	● CAN_STBY



Pin	Symbol	IO	Function
			● SPI0_MOSI ● ENET_PHY_INT ● TOUCH14 ● RGB_B4 ● I8080_D1 ● COM1 ● I2S2_DIN
36	P44	I/O	● CAN_TX ● SPI0_SCK ● RGB_B6 ● I8080_D3 ● COM3 ● I2S2_SCK
37	P41	I/O	● UART2_TX ● I2S1_SYNC ● LIN_TXD ● SC_IO ● RGB_G3 ● I8080_D6



Pin	Symbol	IO	Function
			● SEG2
38	P40	I/O	● UART2_RX ● I2S1_SCK ● LIN_RXD ● SC_CLK ● RGB_G4 ● I8080_D7 ● SEG3
39	GND	P	Power reference ground
40	GND	P	Power reference ground
41	P21	I/O	● I2C0_SDA ● SWDIO ● ADC6 ● RGB_R5 ● I8080_D8 ● SEG9
42	P48	I/O	● ENET_MDIO ● RGB_R2



Pin	Symbol	IO	Function
			● I8080_D16
43	P50	I/O	● ENET_RXD1 ● RGB_R0
44	P25	I/O	● IRDA ● ADC1 ● QSPI0_IO1 ● RGB_G6 ● I8080_WRX ● SEG5
45	P51	I/O	● ENET_RDV ● RGB_G1
46	P27	I/O	● CIS_MCLK ● CLK_AUXS_CIS ● ENET_PHY_INT ● QSPI0_IO3 ● SEG17
47	P29	I/O	● CIS_PCLK ● ENET_MDC



Pin	Symbol	IO	Function
			● TOUCH3 ● SEG19
48	P31	I/O	● CIS_VSYNC ● UART2_TX ● LIN_TXD ● TOUCH5 ● SC_IO ● SEG21
49	P33	I/O	● CIS_PXD1 ● ENET_RXD0 ● TOUCH7 ● TOUCH7 ● SEG23
50	P35	I/O	● CIS_PXD3 ● ENET_RXDV ● TOUCH9 ● SPI0_MOSI ● SEG25



Pin	Symbol	IO	Function
51	P37	I/O	● CIS_PXD5 ● ENET_TXD1 ● TOUCH11 ● SEG27
52	P39	I/O	● CIS_PXD7 ● I2C1_SDA ● ENET_REF_CLK ● TOUCH13 ● COM5 ● SEG29
53	P09	I/O	● I2S0_DOUT ● DMIC_DAT ● 32K_XI
54	P08	I/O	● I2S0_DIN ● DMIC_CLK ● ADC10 ● 32K_XO
55	P07	I/O	● I2S0_SYNC



Pin	Symbol	IO	Function
			● QSPI1_IO3
56	P06	I/O	● I2S0_SCK ● QSPI1_IO2
57	P05	I/O	● SPI1_MISO ● SDIO_DATA1 ● COM7 ● QSPI1_IO1 ● SEG31
58	P04	I/O	● SPI1_MOSI ● SDIO_DATA0 ● COM6 ● QSPI1_IO0 ● SEG30
59	P03	I/O	● SPI1_CSN ● SDIO_CMD ● SC_VCC ● QSPI1_CS
60	P02	I/O	● SPI1_SCK



Pin	Symbol	IO	Function
			● SDIO_CLK ● SC_RSTN ● LIN_SLEEP ● QSPI1_SCK
61	P12	I/O	● UART0_RTS ● TOUCH0 ● ADC14
62	P13	I/O	● UART0_CTS ● TOUCH1 ● ADC15
63	GND	P	Power reference ground
64	VIO	AO	GPIO LDO output
65	GND	P	Power reference ground
66	P14	I/O	● SDIO_CLK ● SPI0_SCK ● I2C1_SCL ● RGB_DCLK



Pin	Symbol	IO	Function
			● I8080_D15 ● SEG16
67	P17	I/O	● SDIO_DATA1 ● SPI0_MISO ● RGB_HSYNC ● I8080_D12 ● SEG13
68	P19	I/O	● SDIO_DATA3 ● RGB_R7 ● I8080_D10 ● SEG11
69	P54	I/O	● ENET_TXEN ● RGB_B1
70	P47	I/O	● SPI0_MISO ● ENET_MDC ● TOUCH15 ● RGB_B3 ● I8080_D0



Pin	Symbol	IO	Function
			● COM0 ● I2S2_DOUT
71	P45	I/O	● CAN_RX ● SPI0_CSN ● RGB_B5 ● I8080_D2 ● COM2 ● I2S2_SYNC
72	P43	I/O	● I2C1_SDA ● I2S1_DOUT ● SC_VCC ● RGB_B7 ● I8080_D4 ● SEG0
73	P42	I/O	● I2C1_SCL ● I2S1_DIN ● LIN_SLEEP ● SC_RSTN



Pin	Symbol	IO	Function
			• RGB_G2 • I8080_D5 • SEG1
74	GND	P	Power reference ground
75	GND	P	Power reference ground

Notes:

- The maximum input level for ADC pins is 1.1 V. It is recommended to use M Ω level external voltage-divider resistors, and place a 100nF capacitor to ground close to the ADC pins for filtering.
- P stands for Power pin
- I/O stands for Input/Output pin.
- AO stands for Analog Output pin.
- AI stands for Analog Input pin.
- For more details on GPIO functions, please refer to the chip datasheet.



5. Electrical Parameters

5.1 Absolute Electrical Parameters

Parameter	Description	Min	Max	Unit
Ts	Storage Temperature	-55	125	°C
VBAT	Supply Voltage	-0.3	3.6	V
ESD Voltage (Machine Model)	TAMB-25°C	-200	200	V
ESD Voltage (Machine Model)	TAMB-25°C	-4	4	KV

5.2 Operating Conditions

Parameter	Description	Min	Typ	Max	Unit
Ta	Operating Temperature	-40	-	85	°C
VCC	Working Voltage	2.0	3.3	3.6	V
VOL	IO low level output	VSS	-	VBAT+0.3	V



Parameter	Description	Min	Typ	Max	Unit
VOH	IO high-level output	VBAT-0.3	-	VBAT	V
I _{max}	IO drive current	-	6	20	mA

5.3 Wi-Fi Transmission power consumption

Power consumption during continuous TX

Symbol	Mode	Rate	TX Power	Typ	Unit
IRF	11b	11Mbps	+17dBm	322	mA
IRF	11g	54Mbps	+15dBm	275	mA
IRF	11n	MCS7	+14dBm	265	mA
IRF	11AX	MCS7	+14dBm	264	mA

5.4 Wi-Fi RX power consumption

Power consumption during continuous RX



Symbol	Mode	Rate	Typ	Unit
IRF	17 dBm, 802.11b	11Mbps	23	mA
IRF	14 dBm, 802.11g	54Mbps	23	mA
IRF	12 dBm 802.11n	MCS7	23	mA

5.5 Power consumption in working mode

Module power consumption

Parameter	conditions	Min	Typ	Max	Unit
Bluetooth network status	The module is in Bluetooth network configuration, and the Wi Fi indicator light is flashing slowly	5.9	-	290	mA
Fast connect network status (AP network)	The module is in a hotspot distribution network state, and the Wi Fi indicator light is flashing slowly	18	-	290	mA
Quick connect distribution network status (EZ distribution)	The module is in a fast connect network state, and the Wi Fi indicator light flashes rapidly	TBD	-	TBD	mA



network)					
Network connection status	The module is in a networked working state, indicator light is constantly on	5.6	-	286	mA
Weak network connection status	The module and hotspot are in a weak network connection state, and the WiFi indicator light is constantly on	5.6	-	290	uA
Network disconnection status	The module is in a disconnected working state, and the WiFi indicator light is constantly off	24	-	287	uA
Deep sleep current	All main logic is powered off, only the AON counter is working		5		uA
ShutDown Current	CEN=0		1		uA
Note: All measurement results were obtained at room temperature and 3.3V voltage					

Note: The power consumption of this test data may vary under different firmware versions

6. RF characteristics

6.1 Wi-Fi output power

RF basic characteristics



Parameter	conditions	Min	Typ	Max	Unit
Operating frequency		2412		2484	MHz
Transmission frequency (EVM meets the standard requirements)	HT20 MCS7		16		dBm
	54 Mbps OFDM		17		dBm
	11Mbps DSSS		19		dBm

6.2 Wi-Fi reception sensitivity

RX Continuous sensitivity

Parameter	conditions	Min	Typ	Max	Unit
Operating frequency		2412		2484	MHz
Sensitivity	HT20 MCS7		-72		dBm
	54 Mbps OFDM		-75		dBm
	6 Mbps OFDM		-91		dBm
	11 Mbps DSSS		-88		dBm
	1 Mbps DSSS		-99		dBm
Neighbor channel suppression ratio	HT20 MCS7		25		dB
	54 Mbps OFDM		26		dB
	11 Mbps DSSS		40		dB



6.3 BLE Receiving characteristics

Parameter	conditions	Min	Typ	Max	Unit
Operating frequency		2402		2480	MHz
Air speed			1		Mbps
Sensitivity				-97	dBm
Maximum RF signal input		-10			dBm
intermodulation				-23	dBm
Common channel suppression ratio C/I			10		dB
Neighbor channel suppression ratio C/I	+1MHz		0		dB
	-1MHz		0		dB
	+2MHz		-20		dB
	-2MHz		-27		dB
	+3MHz		-25		dB
	-3MHz		-36		dB
Out of band	30 MHz ~2000 MHz	-10			dB



	2000 MHz ~2400 MHz	-20			dB
	2500 MHz ~3000 MHz	-10			dB
	3000 MHz ~12.5 GHz	-10			dB

6.4 BLE Launch characteristics

Parameter	conditions	Min	Typ	Max	Unit
Operating frequency		2402		2480	MHz
Air speed			1		Mbps
Transmit power		-20	6	15	dBm
20dB bandwidth BW			1		MHz
Freq Offset		-150		150	KHz
Max Drift		-50		50	KHz
Drift Rate			80	400	Hz/us
Δf_{1avg}		225	244	275	KHz
Δf_{2max}		185	195		KHz
$\Delta f_{1avg}/\Delta f_{2avg}$		0.8	0.85		
Adjacent channel	2MHz Offset		-45	-20	dBm
	≥ 3 MHz Offset		-47	-30	dBm



transmission					
power					

7. Antenna Information

7.1 Antenna type

The BX7258ai module defaults to a PCB antenna and also supports IPEX external antennas

7.2 Reduce antenna interference

When using PCB based antennas, to ensure optimal WiFi performance, it is recommended that the distance between the module antenna and other metal components be at least 16mm.

8. Production Guidance

8.1 Production Guide

The storage conditions for the factory modules are as follows:



- The shelf life of products in dry packaging should be 6 months from the date of packaging sealing.

Notes:

- During the entire production process, operators at each workstation must wear electrostatic rings.
- During operation, take strict precautions to prevent the module from getting wet or contaminated.

8.2 Precautions

A. During the application of the module, please pay attention to avoiding the influence of interference sources such as power amplifiers and boost circuits on the module, and avoid the module power supply circuit forming a series circuit with high-power circuit units, in order to improve the overall signal-to-noise ratio of the machine.

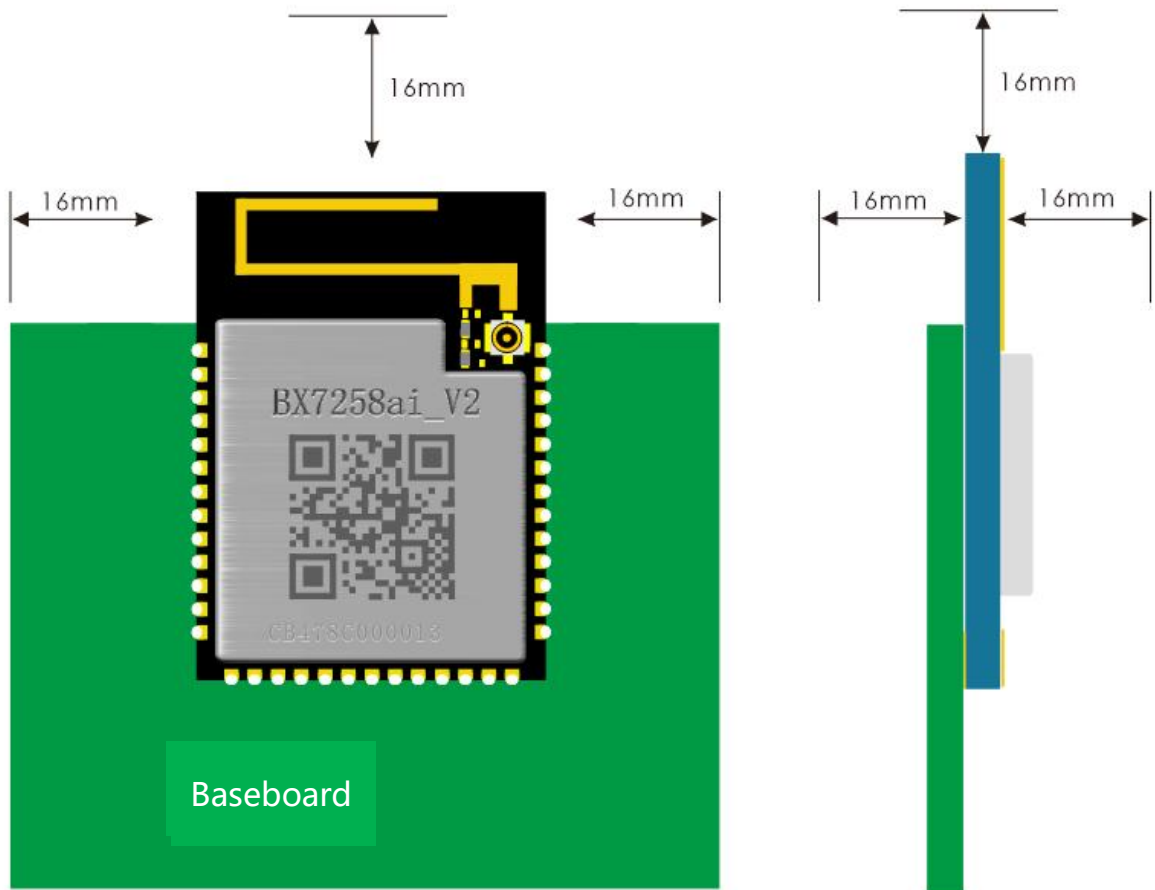
B. Wireless signals are greatly affected by the surrounding environment, and obstacles such as trees and metals can absorb wireless signals to a certain extent. Therefore, in practical applications, the distance of data transmission is affected to a certain extent.

C. The WIFI module needs to be placed in the casing to match the existing system. As the metal casing has a shielding effect on wireless RF signals, it is recommended not to install it in the metal casing.

D. The antenna part of the WIFI module is the PCB antenna. Due to the weakening of the antenna function caused by metal, it is strictly prohibited to lay the ground or wire under the

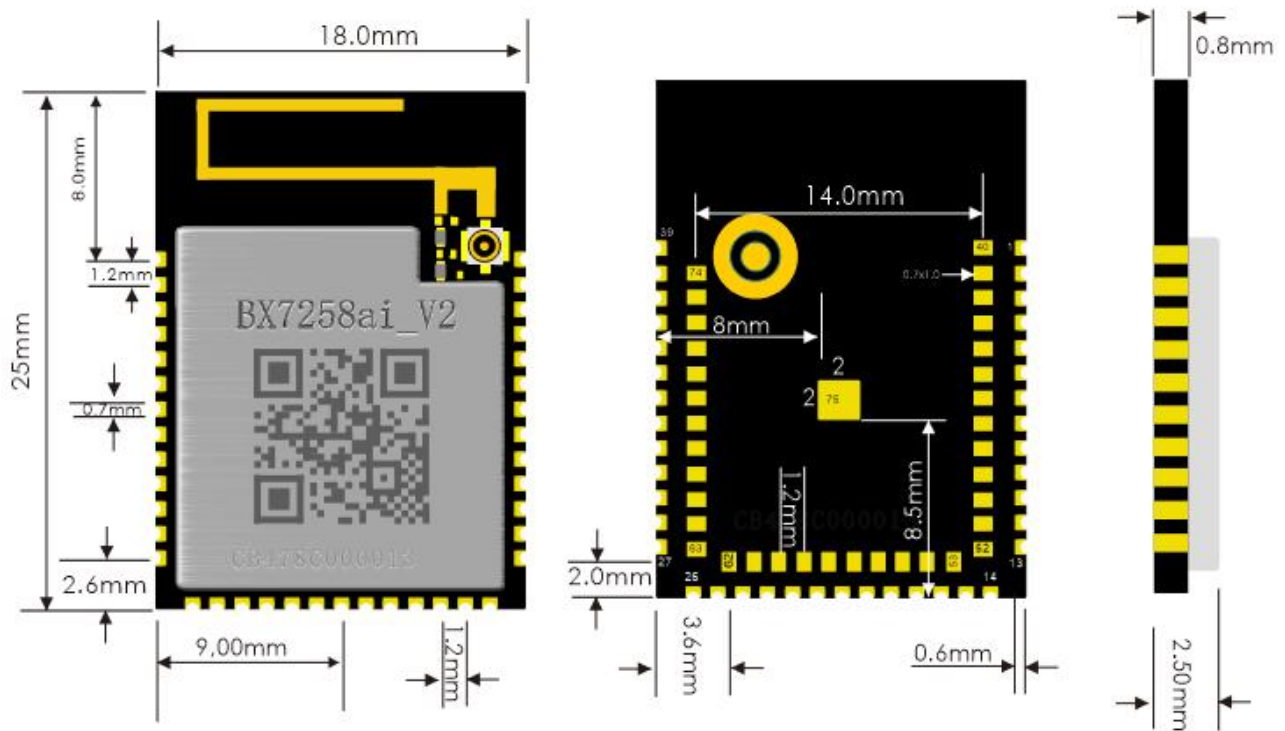


module antenna when laying the module board. It is necessary to ensure that the distance between the motherboard PCB and other metal components is at least 16mm. As shown in the following figure:



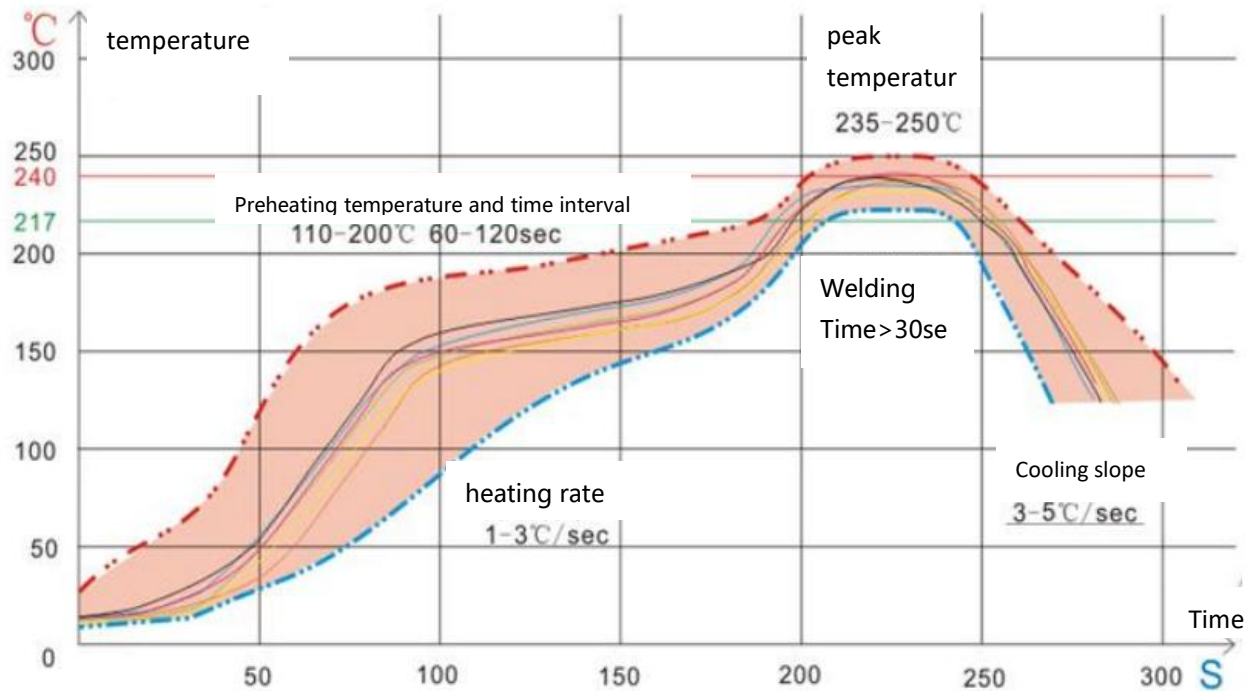


8.3 PCB Recommended packaging





8.4 Recommended return temperature



Explanation for Temperature Changement During Reflow:

Heating zone: temperature: <150 °C, time: between 60-90 seconds, slope controlled between 1-3 °C/s.

Preheating constant temperature zone: temperature: 150 °C~200 °C, time: between 60-120 seconds, slope between 0.3-0.8.

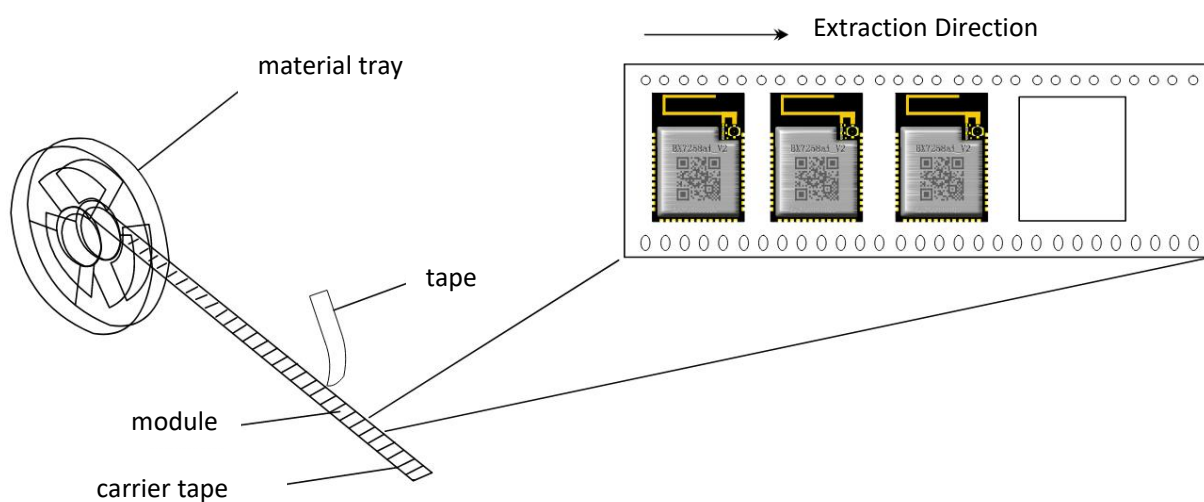
Reflow soldering area: peak temperature 235 °C~250 °C (recommended peak temperature <245 °C), time 30-70 seconds.

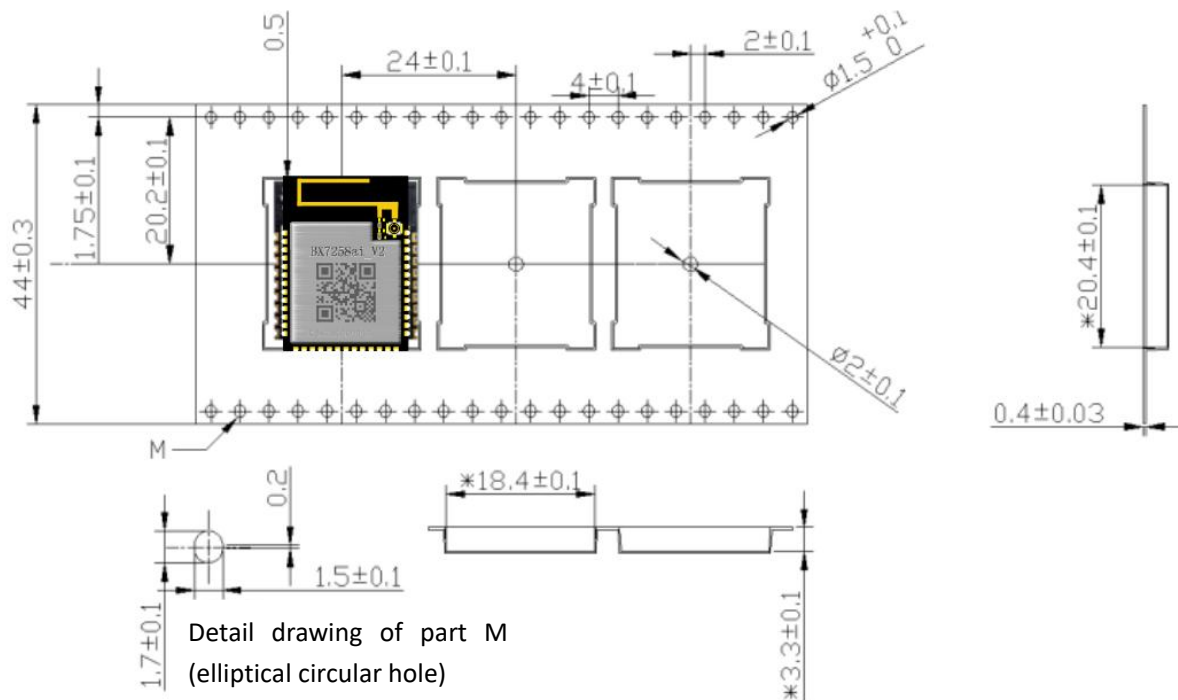
Cooling zone: Temperature: 217 °C~170 °C, slope between 3~5 °C/S.

The solder material is tin silver copper alloy lead-free solder/Sn&Ag&Cu Lead free solder (SAC305)



9. Packaging Information





Each roll contains 1000 products, and each small box contains 1 roll. The large box contains a total of 5 small boxes, with a total of 5000 products per box

10. Authentication Information

10.1 SRRC Certification

This product belongs to a complete non independent operation wireless transmission module. Please indicate the following information in your company's equipment label or manual: This device includes a wireless transmission module with model approval code.



10.2 Bluetooth Authentication

Module Bluetooth QDID:

10.3 RoHS Certification

Module RoHS testing report

11. Module Integration Description

- **End Product Labelling Compliance Information**

When the module is installed in the host device, the FCC ID label must be visible through a window on the final device or it must be visible when an access panel, door or cover is easily removed. If not, a second label must be placed on the outside of the final device that contains the following text: "Contains FCC ID: 2BUSH-BX7258AI" . The FCC ID can be used only when all FCC compliance requirements are met.

- **Information on Test Modes and Additional Testing Requirements**

This transmitter is tested in a standalone mobile RF exposure condition and any co-located or simultaneous transmission with other transmitter(s) class II permissive change re-evaluation or new FCC authorization. Host manufacturer installed this modular with single



modular approval should perform the test of radiated emission and spurious emission according to FCC part 15C, 15.209, 15.207 requirement, only if the test result comply with FCC part 15C, 15.209, 15.207 requirement, then the host can be sold legally.

- **Additional testing, Part 15 Subpart B Disclaimer**

This transmitter modular us tested as a subsystem and its certification does not cover the FCC Part 15 Subpart B rules requirement applicable to the final host. The final host will still need to be reassessed for compliance to this portion of rules requirements if applicable. As long as all conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this modular installed.

- **Manual Information to The End User**

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user' s manual of the end product which integrates this module. The host integrator must follow the integration instructions provided in this document and ensure that the composite system end product complies with the requirements by a technical assessment or evaluation to the rules and to KDB Publication 996369. The host integrator installing this module into their product must ensure that the final composite product complies with the requirements by a technical assessment or evaluation to the rules, including the transmitter operation and should refer to guidance in



KDB Publication 996369. OEM/Host Manufacturer Responsibilities OEM/Host manufacturers are ultimately responsible for the compliance of the Host and Module. The final product must be reassessed against all the essential requirements of the FCC rule such as FCC Part 15 Subpart B before it can be placed on the US market. This includes reassessing the transmitter module for compliance with the Radio and RF Exposure essential requirements of the FCC rules.

- **How to Make Changes - Important Note**

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

12. FCC Caution:

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital



device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation.

If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

The device has been evaluated to meet general RF exposure requirement. The device can be used in portable exposure condition without restriction.